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2813
PATENT
790001-2004

#5
2-21-03
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Yano et al.
U.S. Serial No. : 09/870,085
Filing Date : May 30, 2001
For : **Manufacturing Method of Semiconductor Device**
Examiner: : Thanhha Pham
Group Art Unit : 2813

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231, on January 18, 2002.

Grace L. Pan, Reg. No. 39,440
Name of Applicant, Assignee or Registered Representative

Signature
January 18, 2002
Date of Signature

RESPONSE

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the December 20, 2001 Office Action, which sets a one-month period for response, Applicants provisionally elect, with traverse, the invention of Species A, claims 1 to 6, directed to a method of manufacturing a semiconductor device comprising a step of selectively grinding or polishing the peripheral portion and the beveled portion of the side of the main surface of target substrate including the semiconductor substrate for further prosecution, without prejudice.